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U.S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

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Q. 7		Herman W. Chu, Christian L. Belady and Chandrakant D. Patel, "A Survey of High-performance, High Aspect Ratio, Air Cooled Heat Sinks," International Systems and Packaging Symposium (1999).
Q. 7		Chandrakant D. Patel, "Backside Cooling Solution for High Power Flip Chip Multi-Chip Modules," IEEE ECTC Proceedings 442-449 (May, 1994).

DATE CONSIDERED